Quad 2-Input OR Gate

The MC10103 is a quad 2–input OR gate. The MC10103 provides one gate with OR/NOR outputs.

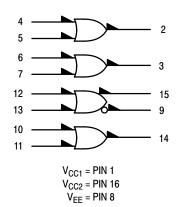
- P_D = 25 mW typ/gate (No Load)
- $t_{pd} = 2.0 \text{ ns typ}$
- t_r , $t_f = 2.0$ ns typ (20%–80%)

ON

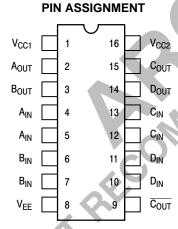
ON Semiconductor

http://onsemi.com

LOGIC DIAGRAM



DIP



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



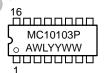
CDIP-16 L SUFFIX CASE 620



MARKING DIAGRAMS



PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping		
MC10103L	CDIP-16	25 Units / Rail		
MC10103P	PDIP-16	25 Units / Rail		
MC10103FN	PLCC-20	46 Units / Rail		

ELECTRICAL CHARACTERISTICS

		Pin				Test Limit	•	1		-
		Under	-30	0°C		+25°C	1	-	5°C	4
Characteristic	Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Un
Power Supply Drain Current	Ι _Ε	8		29		21	26		29	mAd
Input Current	I _{inH}	4*		390			245		245	μΑσ
	I _{inL}	4*	0.5		0.5			0.3		μΑσ
Output Voltage Logic 1	V _{OH}	2 9	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	Vd
Output Voltage Logic 0	V _{OL}	2 9	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	Vd
Threshold Voltage Logic 1	V _{OHA}	2 9	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		Vd
Threshold Voltage Logic 0	V _{OLA}	2 9		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	Vd
Switching Times (50Ω Load)									, 9	ns
Propagation Delay	t ₄₊₂₊ t ₁₂₊₉₋	2 9	1.0 1.0	3.1 3.1	1.0 1.0	2.0 2.0	2.9 2.9	1.0 1.0	3.3 3.3	
Rise Time (20 to 80%)	t ₂₊	2	1.1	3.6	1.1	2.0	3.3	1.1	3.7	
Fall Time (20 to 80%)	t ₂₋	2	1.1	3.6	1.1	2.0	3.3	1.1	3.7	
OEVICE		X								

ELECTRICAL CHARACTERISTICS (continued)

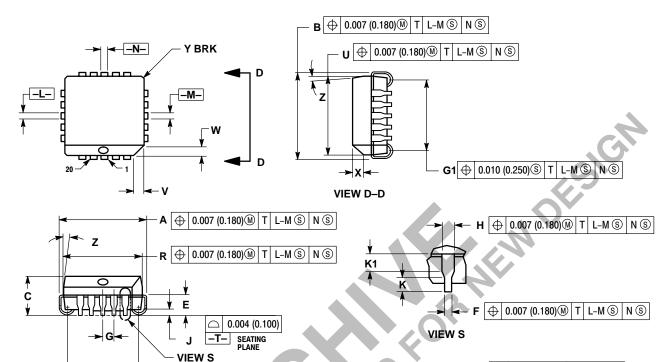
					TEST VOI	TAGE VALU	JES (Volts)		
		@ Test Te	mperature	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
	TEST V	OLTAGE AP	PLIED TO P	INS LISTED I	BELOW				
Characteri	stic	Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	(V _{CC}) Gnd
Power Supply Drain C	Current	ΙE	8					8	1, 16
Input Current		I _{inH}	4*	4*				8	1, 16
		I _{inL}	4*		4*			8	1, 16
Output Voltage	Logic 1	V _{OH}	2 9	4.5				8	1, 16 1, 16
Output Voltage	Logic 0	V _{OL}	2 9	12, 13				8 8	1, 16 1, 16
Threshold Voltage	Logic 1	V _{OHA}	2 9			4, 5	12, 13	8 8	1, 16 1, 16
Threshold Voltage	Logic 0	V _{OLA}	2 9			12, 13	4, 5	8 8	1, 16 1, 16
Switching Times	(50Ω Load)					Pulse In	Pulse Out	−3.2 V	+2.0 V
Propagation Delay		t ₄₊₂₊ t ₁₂₊₉	2 9			4 12	2 9	8 8	1, 16 1, 16
Rise Time	(20 to 80%)	t ₂₊	2			4	2	8	1, 16
Fall Time	(20 to 80%)	t ₂₋	2		> C	4	2	8	1, 16

put under , ned to meet the unted on a printed c .sistor to =2.0 volts. Tes. Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF MICE. NOT PERSON

- IOTES:

 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

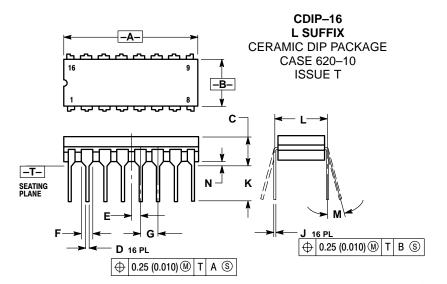
 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.385	0.395	9.78	10.03	
В	0.385	0.395	9.78	10.03	
С	0.165	0.180	4.20	4.57	
Ε	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27	BSC	
Н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.350	0.356	8.89	9.04	
U	0.350	0.356	8.89	9.04	
٧	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
X	0.042	0.056	1.07	1.42	
Y		0.020		0.50	
Z	2°	10°	2°	10 °	
G1	0.310	0.330	7.88	8.38	
K1	0.040		1.02		

PACKAGE DIMENSIONS



NOTES:

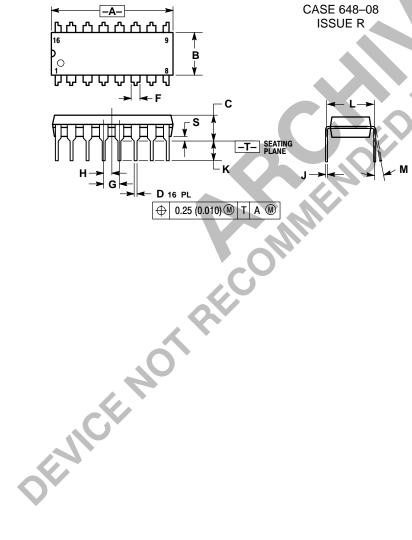
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC
 BODY.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
E	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62 BSC		
М	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
C	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

Notes



Notes





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